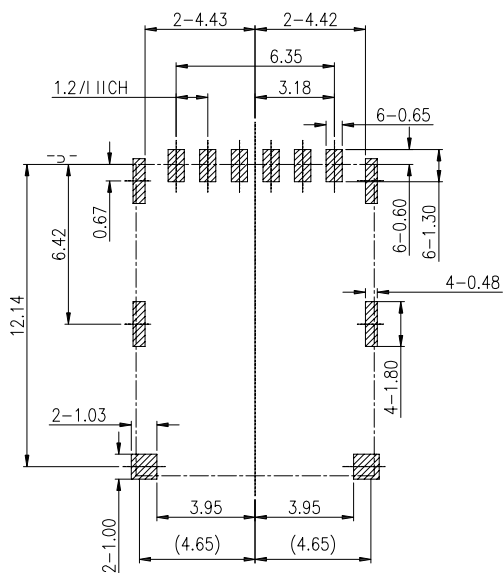
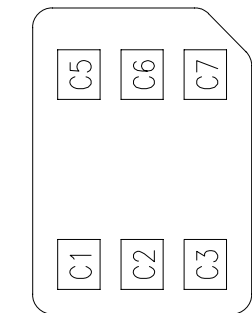
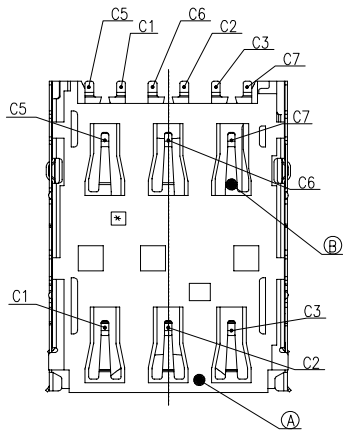


ALL SOLDER-TAIL
 端子焊接平面度: 0.08MAX.
 外壳焊脚平面度: 0.08MAX.



RECOMMENDED P.C.B. LAYOUT
 TOLERANCE (TOP VIEW) ±0.05mm



NANO SIM CARD PAD

SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING: 1A .
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V R.M.S MIN;
 - INSULATION RESISTANCE: 500MΩ MIN.
 - CONTACT RESISTANCE: 100mΩ MAX.(INITIAL)
- LIFE TEST: 1500 CYCLES .
- OTHER GENERAL SPEC. TO REFER "2SM2021-000111F SPEC".
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.
- PACKAGING: TAPE & REEL.
- ⊗ REPRESENT CRITICAL DIMENSIONS.
- ∇ REPRESENT CPK DIMENSIONS.

C	SHELL	1	STAINLESS STEEL,0.10T	NICKEL PLATING OVER ALL
B	CONTACT	1	COPPER ALLOY,0.10T	GOLD FLASH ON CONTACT AREA AND SOLDER AREA 50u" MIN NICKEL UNDER-PLATED
A	HOUSING	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NANO SIM PUSH 1.2H
	CHECKED BY : 马跃	DATE : 2014-02-23	PART NO. : HYC311-SIM06-120
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY : 邱敏	DATE : 2014-02-23	DRAW NO. : HYC-2206011738
			SHEET NO. : 1 OF 1